TROLLEY AND METHOD FOR SUPPORTING COMPONENT OF SUBSTRATE PROCESSING APPARATUS

TECHNICAL FIELD

[0001] The present disclosure relates to a trolley and a method for supporting a component of a substrate processing apparatus.

BACKGROUND

[0002] An example of a processing apparatus that processes a semiconductor wafer (hereinafter, referred to as a wafer), which is a substrate, may include a wafer inspecting apparatus that performs an inspection on the electrical characteristics of a semiconductor device formed on the wafer. Japanese Patent Laid-Open Publication No. 2020-021967 discloses the wafer inspecting apparatus, and discloses that a member that constitutes a cell of the wafer inspecting apparatus is pulled out from the cell and placed on a trolley for maintenance.

SUMMARY

[0003] According to a first aspect of the present invention, there is provided a trolley comprising: a trolley body including a wheel that is freely movable on a floor, and a first support configured to support a component of a substrate processing apparatus that slides in a lateral direction and is pulled out to an outside of the substrate processing apparatus; and a second support connected to the trolley body so as to be freely movable between a first position where a width of the trolley in the lateral direction is a first length and a second position where the width in the lateral direction is a second length longer than the first length, and configured to support the component at the second position together with the first support.

[0003a] According to a second aspect of the present invention, there is provided a method for supporting a component of a substrate processing apparatus, the method comprising:

moving a trolley constituted by a trolley body including a wheel on a floor;

in a state where a second support connected to the trolley body is positioned at a first position and a width of the trolley in the lateral direction is a first length, supporting the component of the substrate processing apparatus pulled out to an outside of the substrate processing apparatus in a lateral direction by a first pull-out amount from the substrate processing apparatus, by a first support provided in the trolley body;

positioning the second support at a second position, and setting the width of the trolley in the lateral direction to a second length longer than the first length; and

in a state where the width of the trolley in the lateral direction is set to the second length, supporting the component of the substrate processing apparatus pulled out to the outside of the substrate processing apparatus in the lateral direction by a second pull-out amount larger than the first pull-out amount from the substrate processing apparatus, by the first support and the second support.

[0004] The foregoing summary is illustrative only and is not intended to be in any way